



# STU664S STD664S

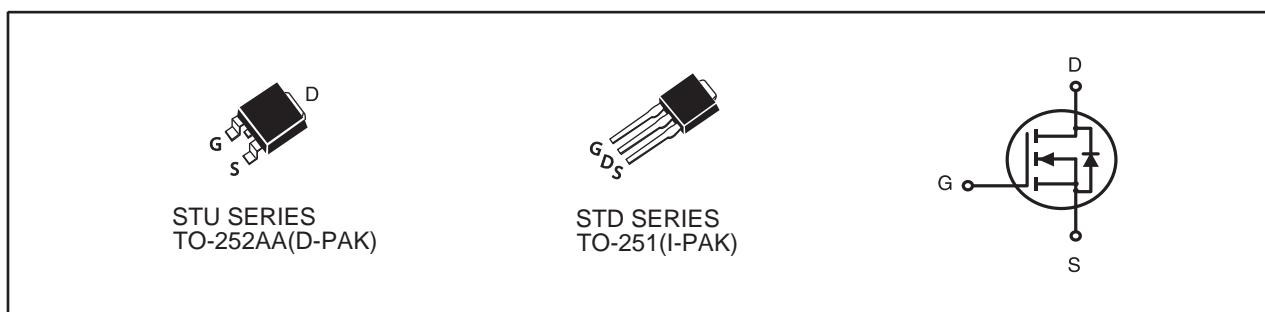
Ver 1.0

## N-Channel Logic Level Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY		
V <sub>DSS</sub>	I <sub>D</sub>	R <sub>DSON</sub> (mΩ) Max
60V	30A	20 @V <sub>GS</sub> =10V

### FEATURES

- Super high dense cell design for low R<sub>DSON</sub>.
- Rugged and reliable.
- TO-252 and TO-251 Package.



### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub>=25°C unless otherwise noted)

Symbol	Parameter	Limit	Units
V <sub>DS</sub>	Drain-Source Voltage	60	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Drain Current-Continuous <sup>a</sup>	30	A
		24	A
I <sub>DM</sub>	-Pulsed <sup>a</sup>	88	A
E <sub>AS</sub>	Single Pulse Avalanche Energy <sup>c</sup>	100	mJ
P <sub>D</sub>	Maximum Power Dissipation	42	W
		27	W
T <sub>J</sub> , T <sub>STG</sub>	Operating Junction and Storage Temperature Range	-55 to 150	°C

### THERMAL CHARACTERISTICS

R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case	3	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	50	°C/W

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## ELECTRICAL CHARACTERISTICS ( $T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>OFF CHARACTERISTICS</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	60			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =48V , V <sub>GS</sub> =0V			1	uA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> = ±20V , V <sub>DS</sub> =0V			±100	nA
<b>ON CHARACTERISTICS</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	2	2.6	4	V
R <sub>Ds(ON)</sub>	Drain-Source On-State Resistance	V <sub>GS</sub> =10V , I <sub>D</sub> =15A		16	20	m ohm
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> =10V , I <sub>D</sub> =15A		22		S
<b>DYNAMIC CHARACTERISTICS</b> <sup>b</sup>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V,V <sub>GS</sub> =0V f=1.0MHz		2190		pF
C <sub>oss</sub>	Output Capacitance			140		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			105		pF
<b>SWITCHING CHARACTERISTICS</b> <sup>b</sup>						
t <sub>D(ON)</sub>	Turn-On Delay Time	V <sub>DD</sub> =30V I <sub>D</sub> =1A V <sub>GS</sub> =10V R <sub>GEN</sub> = 6 ohm		47		ns
t <sub>r</sub>	Rise Time			31		ns
t <sub>D(OFF)</sub>	Turn-Off Delay Time			62		ns
t <sub>f</sub>	Fall Time			13		ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =30V,I <sub>D</sub> =15A,V <sub>GS</sub> =10V		36		nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =30V,I <sub>D</sub> =15A, V <sub>GS</sub> =10V		6		nC
Q <sub>gd</sub>	Gate-Drain Charge			12		nC
<b>DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS</b>						
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V,I <sub>s</sub> =6A		0.81	1.3	V
<b>Notes</b>						
a.Drain current limited by maximum junction temperattrue.						
b.Guaranteed by design, not subject to production testing.						
c.Starting T <sub>J</sub> =25°C,L=0.5mH,V <sub>DD</sub> = 30V.(See Figure13)						

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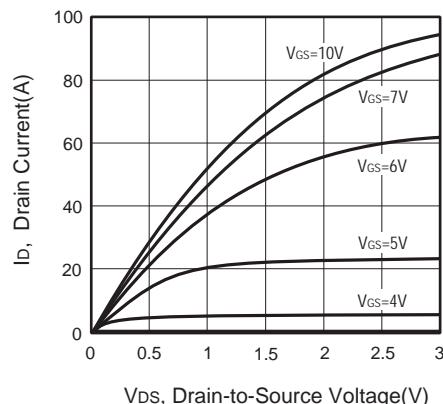


Figure 1. Output Characteristics

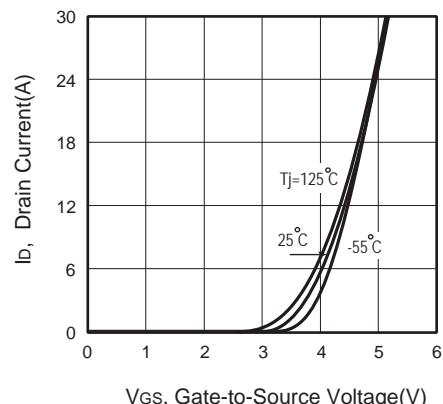


Figure 2. Transfer Characteristics

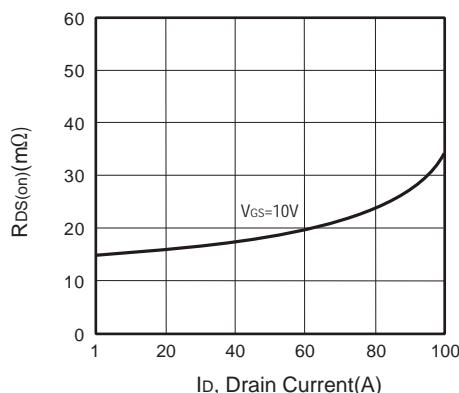


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

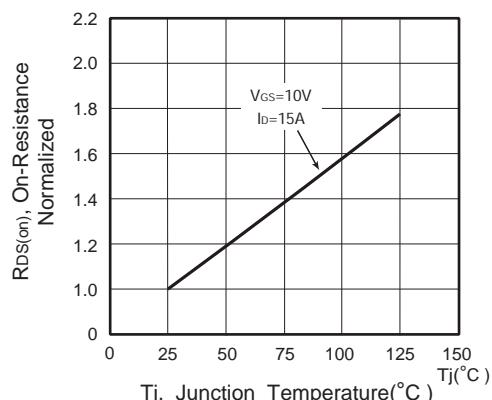


Figure 4. On-Resistance Variation with Drain Current and Temperature

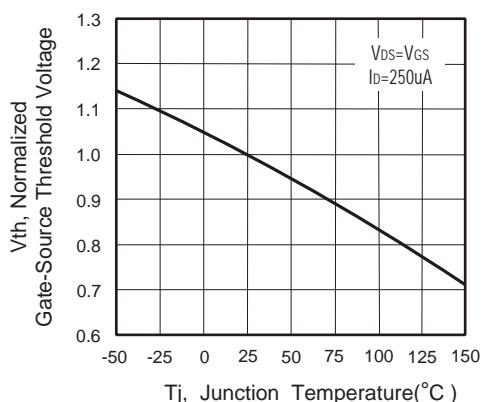


Figure 5. Gate Threshold Variation with Temperature

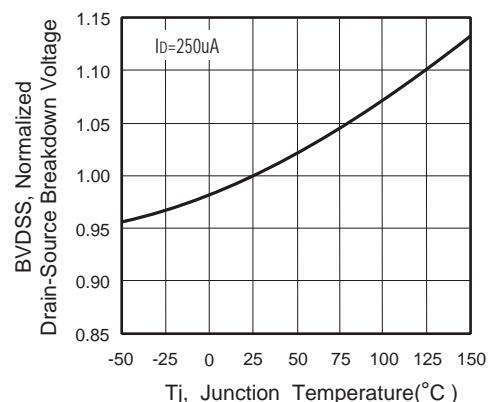


Figure 6. Breakdown Voltage Variation with Temperature